



PRODUCT CHANGE NOTIFICATION

PCN NUMBER: 042503
DATE: 23 July 2003
SUBJECT: AZM CHANGE NOTIFICATION REGARDING

AZ10/100ELT20L
AZ10ELT20D AZ100ELT20D
AZ10ELT20T AZ100ELT20T
AZ100ELT20N

TITLE: Change to smaller die area and larger wafer diameter, porting to equivalent process at different foundry and foundry location, design change to simplify 10/100 selection, design change to improve ESD

EFFECTIVE DATE: 1 May 2004

AFFECTED CHANGE CATEGORIES: Wafer diameter and process, foundry and foundry location, die dimensions, pad locations, design changes

AFFECTED PRODUCTS: AZ10ELT20 and AZ100ELT20 in the following packages: D, T, L, N

DISCLAIMER: AZM considers this change approved unless specific conditions of acceptance are provided within 30 days of this notice. To do so, please contact AZM.

DESCRIPTION AND PURPOSE: The previous foundry, AGERE, has terminated the process. AZM has reached a point where inventory is substantially depleted and has ported the design to an equivalent, qualified production process at ZARLINK (formerly Plessey) in Swindon, UK, on larger diameter wafers. AZM took the opportunity to reduce die area to an area identical to other AZM products, e.g., AZ100EL16VO and others in order to be able to offer the replacement device also in the 2x2x0.75mm MLP package (suffix "N"). The 10/100 selection was reduced from 2 pads to 1 pad and ESD performance was improved. No changes were made to function or electrical dc or ac specifications or behavior.

QUALIFICATION STATUS: Process and product are qualified and released to production.

ELECTRICAL CHARACTERISTICS: No changes.

PACKAGE: No changes.